

Abstract of the Disclosure

An adhesive tape for the removal of a resist includes a curing adhesive layer having an initial tensile modulus of not smaller than 10 MPa at 100°C after cured provided on a supporting base material, and/or an adhesive layer provided on a supporting base material having a flexural stiffness of not smaller than 1×10^{-4} (N·m) per unit width.

2025.01.02 10:55:00